



**AAEON Technology INC.**  
ISO-9001/ISO-14001 Certified  
Industrial Automation PCs

# **SBC-675**

## **Thermal Image Analysis Report**

**Release Date: JAN.08, 2001**

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**Issue Stamp**

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**QA Manager**

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**QE Manager**

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**Test Engineer**

# Thermal Image Analysis

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**I . Model Name: SBC-675 Rev.B0.1**

**II . Description: Socket 370 Full-size CPU Card with LCD, Ethernet, High Drive, & SSD**

**III . Date: JAN. 08, 2001**

**IV. Measure Site: AAEON QE Dept.**

**V . Issued by : Kuochen Huang**

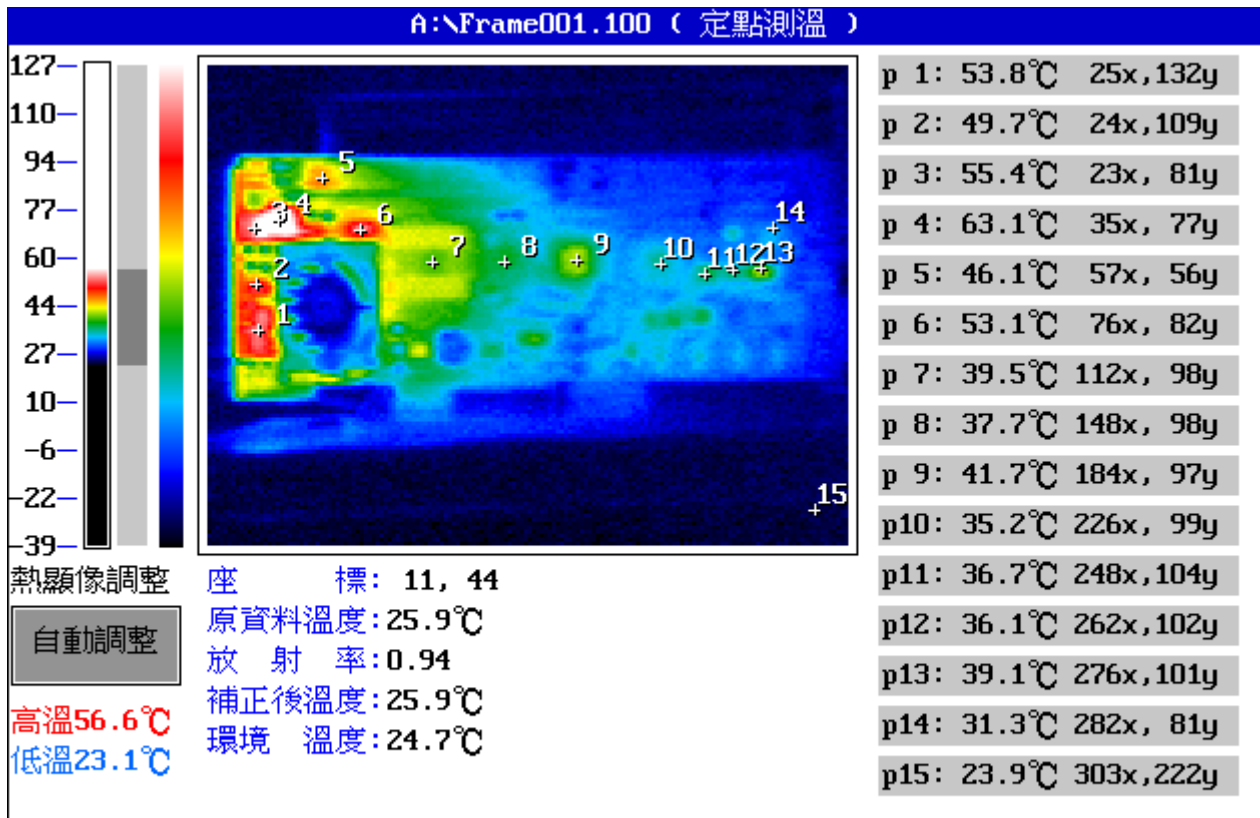
**VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: 23.9 degrees C**
- **CPU: Pentium III 700MHz/100MHz**
- **RAM: 64 MB**
- **Hardware: DiskOnChip**
- **Application Software: QAPLUS/FE V5.5**
- **Take Picture Time: Power on 30 minutes after**

# Temperature Profile Test:

Component Side:



Point	Position	Describe	Ts	Tm	Note
1	Q3	PHB 50N03LT PHm0009E4	175°C	53.8°C	
2	L18	27H/20A		49.7°C	
3	U3	0019 LTC1753CG N12200	150°C	55.4°C	
4	Q1	AMS 1083CM 0017	150°C	63.1°C	
5	DIM1	NEC JAPAN D4564841G5-A08-9JF 9927L5W323		46.1°C	
6	U2	W40S01-04H B025 1018TD	70°C	53.1°C	
7	U6	Intel 82443BX		39.5°C	
8	U35	GD82559 L028LY72		37.7°C	
9	U8	CHIPS B69000B4 0020-b		41.7°C	
10	U9	Intel PCIsot FW82371EB L0071E99 SL37M		35.2°C	
11	U10	14S8416816		36.7°C	
12	U11	P99AK DM74ALS 245AWM		36.1°C	
13	U12	S46 GD75232D		39.1°C	
14	U4	Winbond W83977TF-AW		31.3°C	
15		The Room Temperature		23.9°C	

**1. Operation Temperature (°C):**

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)